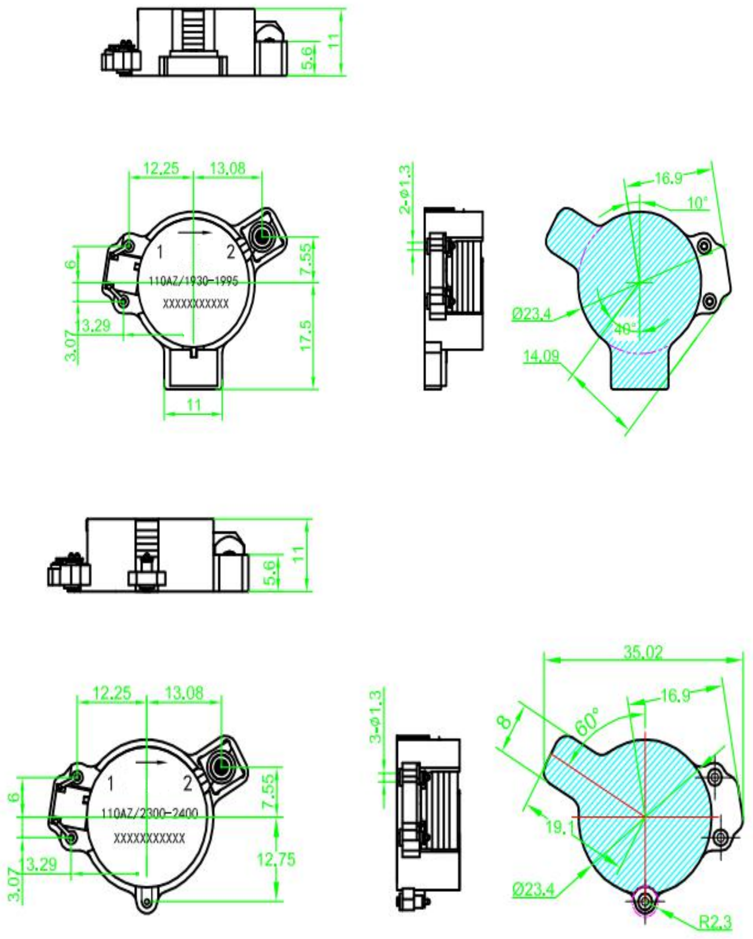
SMD Isolator 110A Series

1.Features

UMTS, LTE Band
PCB Soldering Re-flow
Wide Operation Temperature Range -45 ~ 125℃
Compact Package Design for PCB Applications

2.Dimensions



Unit:mm

3.Specifications

Part No.	Frequency (MHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	Return Loss	Power	IMD (@2X50W)
	F1	F2	(MHz)	(MHz)	(dB) MIN	(dB) MAX	(dB) MIN	(W)	(-dBc) MAX
G110AZ100/791-	791	821	806	30	22	0.25	23	80	-65
G110AZ100/925-	925	960	943	35	22	0.25	23	80	-69
G110AZ100/1805-	1805	1880	1843	75	22	0.20	23	80	-69
G110AZ100/1930-	1930	2020	1975	90	22	0.20	23	80	-69
G110AZ100/2110-	2110	2200	2155	90	22	0.20	23	80	-69
G110AZ100/2620-	2620	2690	2655	70	22	0.20	23	80	-69
H110AZ100/2300-	2300	2400	2350	100	22	0.25	23	80	-69
H110AZ100/2496-	2496	2690	2593	194	22	0.25	23	80	-69

1.Features

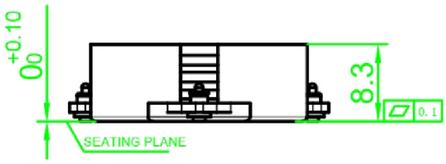
UMTS, LTE Band

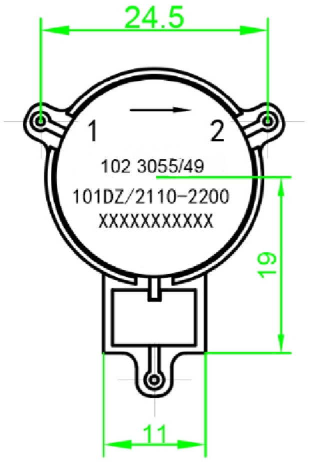
PCB Soldering Re-flow

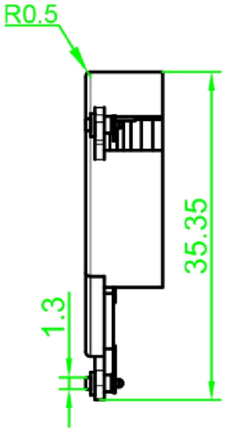
Wide Operation Temperature Range -45 ~ 125℃

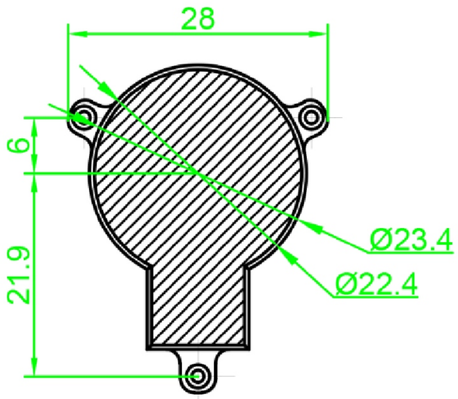
Compact Package Design for PCB Applications

2.Dimensions 尺寸展示









Unit:mm

3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
G101DZ100-30(859-894)MHz	0.859	0.894	0.8765	0.035	22	0.2	1.13	130	-75

1.Features

UMTS, LTE Band

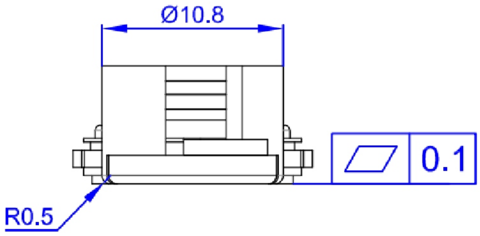
PCB Soldering Re-flow

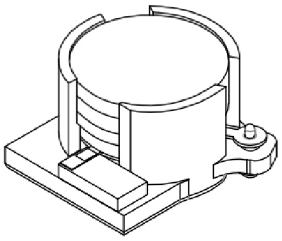
Wide Operation Temperature Range -45 ~ 125℃

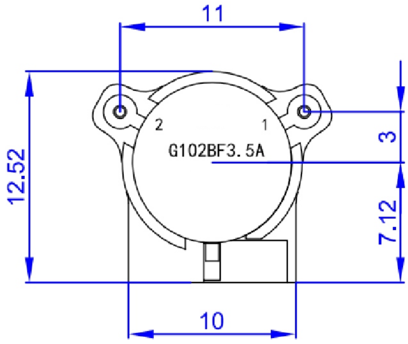
Compact Package Design for PCB Applications

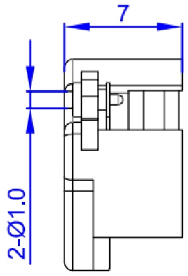
2.Dimensions

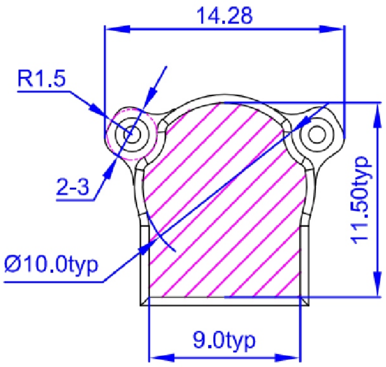
Unit:mm











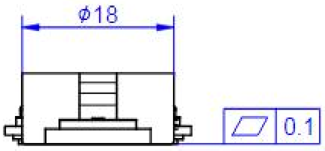
3.Specifications

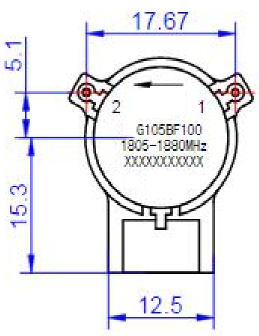
Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
G102BF1.8-2.1G	1.805	2.170	1.9875	0.365	17	0.55	1.33	20	-50
G102BZ2G	1.980	2.010	1.9950	0.030	23	0.3	1.15	20	-65
G102BF2.6G	2.456	2.730	2.5930	0.274	20	0.35	1.17	20	-72

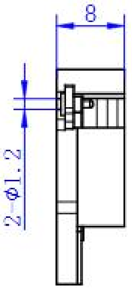
1.Features

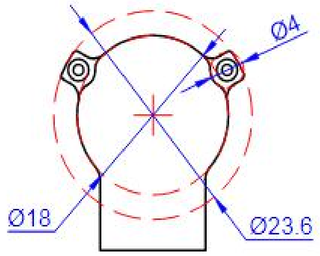
UMTS, LTE Band
PCB Soldering Re-flow
Wide Operation Temperature Range -45 ~ 125℃
Compact Package Design for PCB Applications

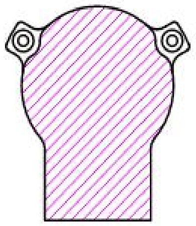
2.Dimensions











3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
G105BZ60-0.0(1480-1526)MH	1.480	1.526	1.5030	0.046	25	0.2	1.12	100	-74
G105BF60-0.0(1840-1900)MHz	1.840	1.900	1.8700	0.060	25	0.2	1.12	100	-74
G105BZ100-0.0(2200-2400)MHz	2.200	2.400	2.3000	0.200	25	0.25	1.12	100	-74
G105BZ60-0.0(2500-2700)MHz	2.500	2.700	2.6000	0.200	22	0.25	1.17	100	-74

1.Features

UMTS, LTE Band

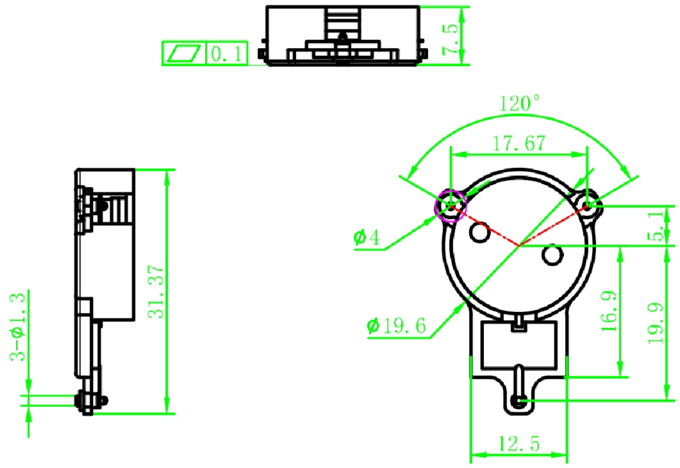
PCB Soldering Re-flow

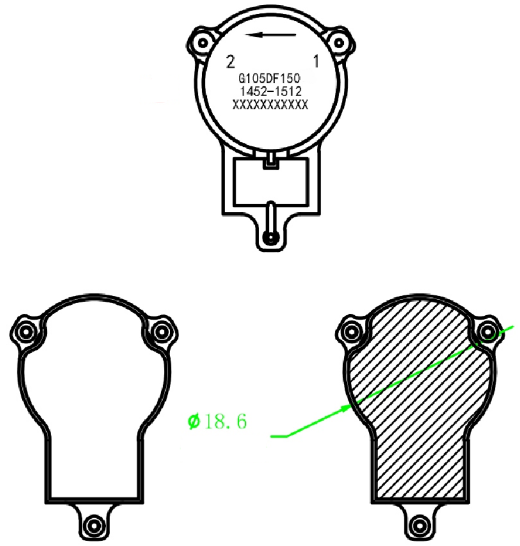
Wide Operation Temperature Range -45 ~ 125℃

Compact Package Design for PCB Applications

2.Dimensions

Unit:mm





3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
G105DF150-30(791-821)MHz	0.721	0.821	0.7710	0.100	23	0.25	1.19	150	-72
G105DZ150-30(851-894)MHz	0.851	0.894	0.8725	0.043	23	0.25	1.15	150	-70
G105DF150-30(925-960)MHz	0.925	0.960	0.9425	0.035	25	0.35	1.15	150	-72
G105DZ150-30(1805-1880)MHz	1.805	1.880	1.8425	0.075	28	0.15	1.12	150	-72
G105DZ150-30(2110-2170)MHz	2.110	2.170	2.1400	0.060	25	0.2	1.12	150	-76
G105DF150-30(2600-2720)MHz	2.600	2.720	2.6600	0.120	28	0.15	1.12	150	-72

- Frequency Range 600MHz - 3.8GHz,from 5% to Full Bandwidth.
- Military, Space and Commercial Applications, Reflowable.
- **Low insertion Loss,High Isolation,High power handling.**
- **Custom Design Available Upon Request.**

Part Number	**Frequency Range (GHz)**	**Bandwidth Max.**	**Insertion Loss Max.(dB)**	**Isolation Min. (dB)**	**VSWR Max.**	**FWD/REV Power (W)**	**Size D×H (mm)**	**Temp. Range (℃)**
HSI24A	600-1300	5%	0.35	23	1.2	100/5	Φ24.2×6.5	-30~+70
		10%	0.4	20	1.25			
HSI18A	1300-3800	5%	0.35	23	1.2	100/5	Φ18.2×6.5	-30~+70
		10%	0.4	20	1.25			
HSI27A	925-960	Full	0.3	23	1.2	100/5	Φ27×10	-30~+85
HSI22A	2110-2170	Full	0.3	23	1.2	100/5	Φ22.9×8.9	-30~+85